SPECIFICATIONS					
CUSTOMER :					
SAMPLE CODE :	SH240320T073-ZAA				
MASS PRODUCTION CODE :	PH240320T073-ZAA				
SAMPLE VERSION :	01				
SPECIFICATIONS EDITION :	003				

LMD-PH240320T073-ZAA (Ver.001)

PKG-PH240320T073-ZAA (Ver.001)

# **Customer Approved** Date:

Approved	Checked	Designer
廖志豪	廖志豪	張 <b>慶</b> 源
Rex Liao	Rex Liao	Yuan Chang

Preliminary specification for design input

Specification for sample approval

(Ver.)

## POWERTIP TECH. CORP.

Headquarters: No.8, 6th Road, Taichung Industrial Park,

PACKAGING NO. (Ver.)

DRAWING NO.

Taichung, Taiwan

台中市 407 工業區六路 8號

TEL: 886-4-2355-8168

FAX: 886-4-2355-8166

E-mail: <a href="mailto:sales@powertip.com.tw">sales@powertip.com.tw</a>

Http://www.powertip.com.tw



# **History of Version**

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
07/30/2018	01	001	New Drawing	-	Yuan
10/02/2018	01	002	First Sample	-	Yuan
12/12/2018	01	003	Modify Contrast ratio	6	Yuan
					<b>\</b>
				<b>-</b>	

Total: 29 Page



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Note: For detailed information please refer to IC data sheet:

Sitronix:ST7789VI (Or Compatible IC)



#### 1. SPECIFICATIONS

# 1.1 Features

## **Main LCD Panel**

Item	Standard Value
Display Type	240 * (R · G · B) * 320 Dots
LCD Type	IPS, Normally Black, Transmissive
Screen size(inch)	2.4 (Diagonal)
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	8 Bit Interface for i80system
Driver IC	Sitronix:ST7789VI (Or Compatible IC)
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer website:
	http://www.powertip.com.tw/news_detail.php?Key=1&cID=1

# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	42.32 (W) * 60.06 (L) * 2.1 (H)	mm

#### **LCD Panel**

Item	Standard Value	
Viewing Area	37.72 (W) * 49.96(L)	mm
Active Area	36.72(W) * 48.96(L)	mm

Note: For detailed information please refer to LCM drawing



# 1.3 Absolute Maximum Ratings

#### **Module**

Item	Symbol	Condition	Min.	Max.	Unit	
System Bower Supply Voltage	VDD -		-0.3	4.6	V	
System Power Supply Voltage	VGH-VGL	GND	0	+30	V	
Logic Input Voltage	VIN	-	-0.3	VDD+0.5	٧	
Operating Temperature	TOP	-	-20	70	°C	
Storage Temperature	TST	-	-30	80	.c	

## 1.4 DC Electrical Characteristics

**Module** GND = 0V,  $Ta = 25 ^{\circ}C$ 

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VDD		-	2.8	-	٧
Input High Voltage	VIH	-	0.7*VDD	-	VDD	٧
Input Low Voltage	VIL	·	GND	-	0.3*VDD	٧
Output High Voltage	Vон	IOH=-0.1mA	0.8*VDD	-	VDD	٧
Output Low Voltage	Vol	IOL=0.1mA	GND	-	0.2*VDD	٧
Supply Current	IDD	VDD = 2.8V Pattern= Full display *1	-	9	12	mA

Note 1: Maximum current display





# 1.5 Optical Characteristics

## **TFT LCD panel**

VDD= 2.8 V, Ta=25 ℃

Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response time	Rise Fall	Tr+Tf	Ta = 25 ℃ θX, θY = 0°	-	35	45	ms	Note2
	Тор	θΥ+		-	80	-		
Viouring angle	Bottom	θΥ-	CR ≥ 10	-	80	-	Dog	
Viewing angle	Left	θХ-	CH 2 10	-	80	-	Deg.	Note4
	Right	θХ+		ı	80	-		
Contrast rati	0	CR	Ta = 25 ℃ θX , θY = 0°	650	800	-	-	Note3
	\\/hita	Х		0.26	0.31	0.36		
	White	Υ		0.28	0.33	0.38		
0 1 (0)5	Dod	Х		0.59	0.64	0.69		
Color of CIE Coordinate	Red	Υ	Ta = 25℃	0.29	0.34	0.39		Note1
(With LCD)	Green	Χ	$\theta X$ , $\theta Y = 0^{\circ}$	0.28	0.33	0.38	_	Note
(With 200)	Green	Υ		0.56	0.61	0.66		
	Blue	Χ		0.09	0.14	0.19		
	Diue	Υ		0.01	0.04	0.09		
Average Bright	ness							
Pattern=white di	splay	IV	IF=60 mA	160	190	-	cd/m <sup>2</sup>	Note1
(With LCD)	)							
Uniformity (With LCD)		∆B	IF=60 mA	80	-	-	%	Note1



#### Note1:

\*1: \( \triangle B = B(min) / B(max) \* 100%

\*2 : Measurement Condition for Optical Characteristics:

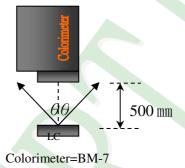
a: Environment: 25°C±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.

b : Measurement Distance:  $500 \pm 50 \text{ mm}$  ,  $(\theta = 0^{\circ})$ 

c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.

d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





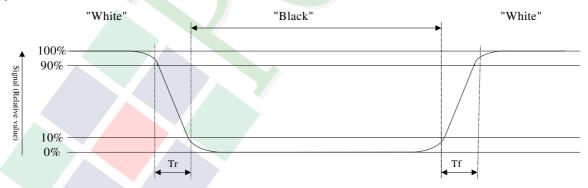
To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

#### Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

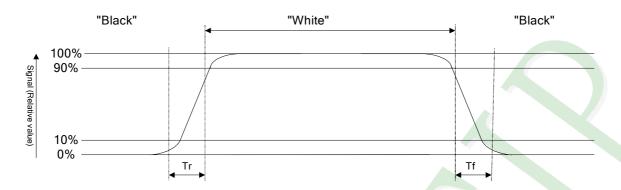
#### Refer to figure as below:

#### Normally White





#### Normally Black



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle: Refer to figure as below:



## 1.6 Backlight & LED Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	- 🔥	75	mA
Reverse Voltage	VR	Ta =25°℃	-	4	V

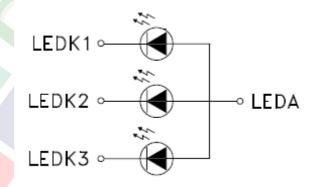
Electrical / Optical Characteristics

= iooti iodi / optiodi oridiaoti						
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		-	3.2	3.5	V
Average Brightness (without LCD)	IV	IF= 60 mA	3200	3830	1	cd/m <sup>2</sup>
Color of CIE Coordinate*1	X		0.24	0.27	0.30	*2
(Without LCD)	Y		0.24	0.27	0.30	2
Color			White			

\*1 : This value will be changed while mass production.

\*2: \( \triangle B=B(min) / B(max) \*100%

B/L Internal Circuit Diagram



Item	Conditions	Description
MTBF (Life Time)	Ta =25°C IF= 60 mA	20000 hrs



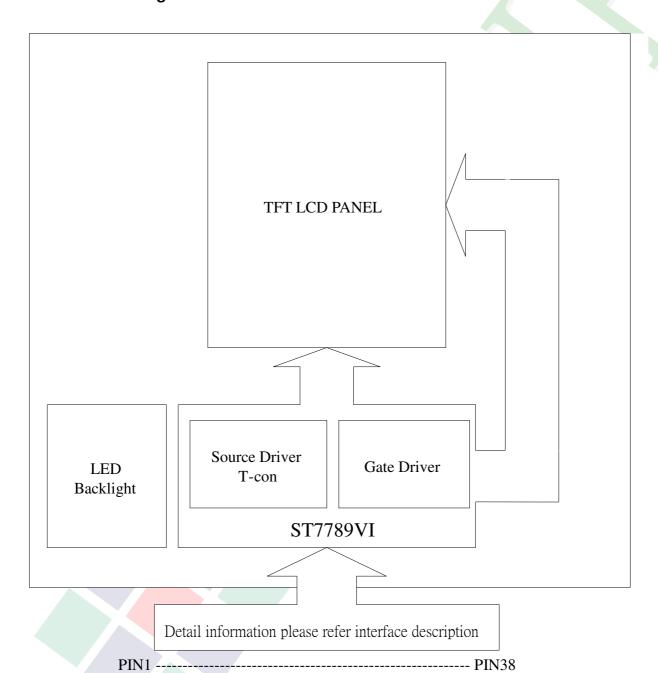
## 2. MODULE STRUCTURE

## 2.1 Counter Drawing

## 2.1.1 LCM Mechanical Diagram

\* See Appendix

## 2.1.2 Block Diagram





**Interface Pin Description** 

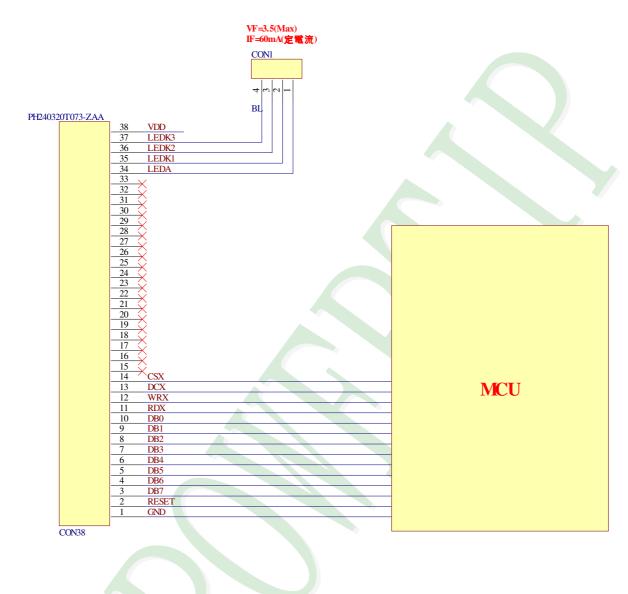
Pin No.	Symbol	Function
1	GND	System Ground.(0V)
2	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low.
3	DB7	Bi-directional data bus.
4	DB6	Bi-directional data bus.
5	DB5	Bi-directional data bus.
6	DB4	Bi-directional data bus.
7	DB3	Bi-directional data bus.
8	DB2	Bi-directional data bus.
9	DB1	Bi-directional data bus.
10	DB0	Bi-directional data bus.
11	RD	Serves as a read signal and MCU read data at the rising edge.
12	/WR	Serves as a write signal and writes data at the rising edge.
13	RS	When RS = '1', data is selected.  When RS = '0', command is selected.
14	/CS	Chip select input pin ("Low" enable).
15	NC	Not Connect.
16	NC	Not Connect.
17	NC	Not Connect.
18	NC	Not Connect.
19	NC	Not Connect.
20	NC	Not Connect.
21	NC	Not Connect.
22	NC	Not Connect.



Pin No.	Symbol	Function
23	NC	Not Connect.
24	NC	Not Connect.
25	NC	Not Connect.
26	NC	Not Connect.
27	NC	Not Connect.
28	NC	Not Connect.
29	NC	Not Connect.
30	NC	Not Connect.
31	NC	Not Connect.
32	NC	Not Connect.
33	NC	Not Connect.
34	LEDA	Power supply for LED Backlight Anode input.
35	LEDK1	Power supply for LED Backlight Cathode input.
36	LEDK2	Power supply for LED Backlight Cathode input.
37	LEDK3	Power supply for LED Backlight Cathode input.
38	VDD	Power supply.(2.8V) .



## **Application Notes:**





#### 2.2.2 Refer Initial code:

MOV ADDRL,#11H CALL WRITE\_COMMAND

CALL DELAY
CALL DELAY
CALL DELAY

MOV ADDRL,#36H
CALL WRITE\_COMMAND
MOV ADDRL,#00H
CALL WRITE\_DATA

MOV ADDRL,#3aH
CALL WRITE\_COMMAND
MOV ADDRL,#05H
CALL WRITE\_DATA

MOV ADDRL,#B2H **CALL** WRITE\_COMMAND MOV ADDRL,#0CH **CALL** WRITE\_DATA MOV ADDRL,#0CH CALL WRITE DATA MOV ADDRL,#00H **CALL** WRITE DATA MOV ADDRL,#33H **CALL** WRITE DATA MOV ADDRL,#33H **CALL** WRITE\_DATA

MOV ADDRL,#B7H
CALL WRITE\_COMMAND
MOV ADDRL,#35H
CALL WRITE\_DATA

MOV ADDRL,#BBH
CALL WRITE\_COMMAND
MOV ADDRL,#20H
CALL WRITE\_DATA

MOV ADDRL,#C0H
CALL WRITE\_COMMAND
MOV ADDRL,#2CH
CALL WRITE\_DATA

MOV ADDRL,#C2H
CALL WRITE\_COMMAND
MOV ADDRL,#01H
CALL WRITE\_DATA

MOV ADDRL,#C3H
CALL WRITE\_COMMAND
MOV ADDRL,#0bH
CALL WRITE\_DATA

MOV ADDRL,#C4H
CALL WRITE\_COMMAND
MOV ADDRL,#20H
CALL WRITE\_DATA



MOV ADDRL,#C6H **CALL** WRITE COMMAND MOV ADDRL,#0fH **CALL** WRITE DATA MOV ADDRL,#D0H **CALL** WRITE COMMAND MOV ADDRL,#A4H WRITE\_DATA **CALL** MOV ADDRL,#A1H **CALL** WRITE DATA MOV ADDRL,#E0H WRITE\_COMMAND **CALL** MOV ADDRL,#F0H **CALL** WRITE\_DATA MOV ADDRL,#06H **CALL** WRITE\_DATA MOV ADDRL,#0AH **CALL** WRITE\_DATA MOV ADDRL,#08H **CALL** WRITE DATA MOV ADDRL,#07H **CALL** WRITE DATA MOV ADDRL.#26H **CALL** WRITE DATA MOV ADDRL,#2BH **CALL** WRITE DATA MOV ADDRL,#34H **CALL** WRITE DATA MOV ADDRL,#44H **CALL** WRITE\_DATA MOV ADDRL,#36H **CALL** WRITE\_DATA MOV ADDRL,#11H **CALL** WRITE\_DATA MOV ADDRL,#12H **CALL** WRITE\_DATA MOV ADDRL,#2DH **CALL** WRITE\_DATA MOV ADDRL,#33H **CALL** WRITE DATA MOV ADDRL.#E1H **CALL** WRITE COMMAND MOV ADDRL,#F0H **CALL** WRITE DATA MOV ADDRL,#03H **CALL** WRITE DATA MOV ADDRL,#08H **CALL** WRITE DATA MOV ADDRL,#09H **CALL** WRITE\_DATA MOV ADDRL,#08H **CALL** WRITE\_DATA MOV ADDRL,#03H **CALL** WRITE\_DATA MOV ADDRL,#2DH **CALL** WRITE\_DATA

MOV

**CALL** 

ADDRL,#42H

WRITE\_DATA



MOV ADDRL,#42H **CALL** WRITE\_DATA MOV ADDRL,#37H **CALL** WRITE DATA MOV ADDRL,#13H WRITE\_DATA ADDRL,#13H WRITE\_DATA ADDRL,#2FH WRITE\_DATA ADDRL,#35H WRITE\_DATA





## 2.3 Timing Characteristics



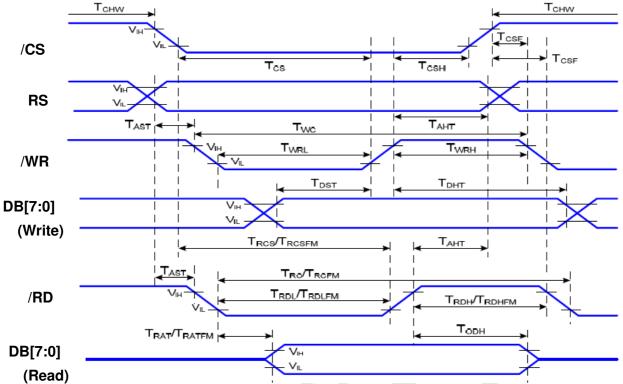


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
	TAST	Address setup time	0		ns	2000111011
RS	Тант	Address hold time (Write/Read)	10		ns	-
	Тснw	Chip select "H" pulse width	0		ns	
	Tcs	Chip select setup time (Write)	15		ns	
/00	Trcs	Chip select setup time (Read ID)	45		ns	
/CS	TRCSFM	Chip select setup time (Read FM)	355		ns	-
	Tosf	Chip select wait time (Write/Read)	10		ns	
	Тсѕн	Chip select hold time	10		ns	
	Twc	Write cycle	66		ns	
/WR	Twrh	Control pulse "H" duration	15		ns	-
,	Twrl	Control pulse "L" duration	15		ns	
	Trc	Read cycle (ID)	160		ns	
/RD (ID)	TRDH	Control pulse "H" duration (ID)	90		ns	When read ID data
	TRDL	Control pulse "L" duration (ID)	45		ns	
/RD	TRCFM	Read cycle (FM)	450		ns	When read from
	TRDHFM	Control pulse "H" duration (FM)	90		ns	
(FM)	TRDLFM	Control pulse "L" duration (FM)	355		ns	frame memory
	TDST	Data setup time	10		ns	
	Тонт	Data hold time	10		ns	
DB[7:0]	TRAT	Read access time (ID)		40	ns	For CL=30pF
	TRATEM	Read access time (FM)		340	ns	
	Торн	Output disable time	20	80	ns	



## **Reset Timing**

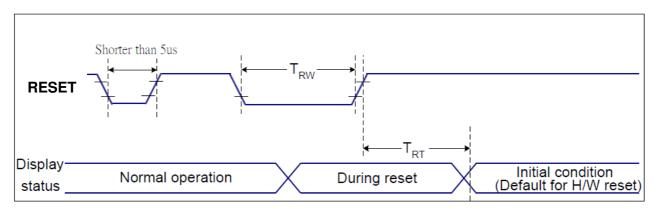


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30  $\sim$  70  $^{\circ}$ 

Related Pins	Related Pins Symbol Parameter		MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESET	TRT Reset cancel	Paget sangel	-	5 (Note 1, 5)	ms
			120 (Note 1, 6, 7)	ms	

**Table 8 Reset Timing** 

#### Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
  - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

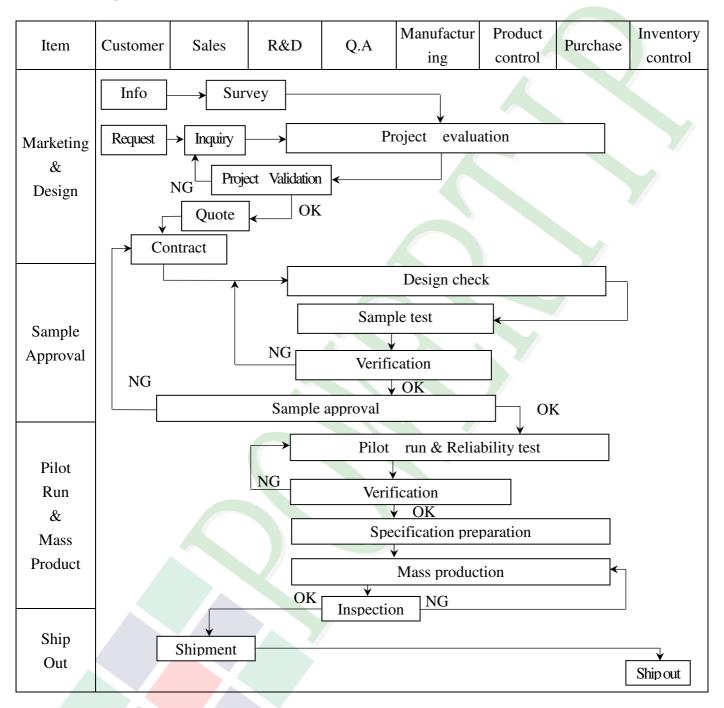
RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
  - 4. Spike Rejection also applies during a valid reset pulse as shown below:

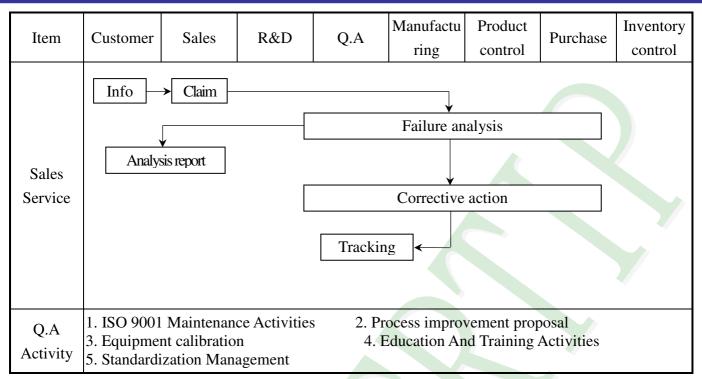


## 3. QUALITY ASSURANCE SYSTEM

## 3.1 Quality Assurance Flow Chart



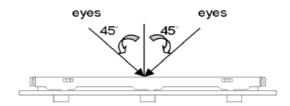




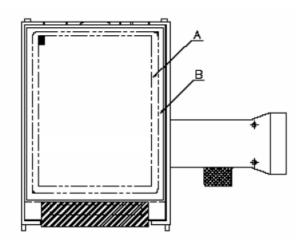


#### 3.2. Inspection Specification

- ◆Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).
- ◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment: Gauge · MIL-STD · Powertip Tester · Sample
- ◆Defect Level: Major Defect AQL: 0,4; Minor Defect AQL: 1,5
- ◆OUT Going Defect Level: Sampling.
- ◆Standard of the product appearance test:
  - a. Manner of appearance test:
  - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
  - (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



## ◆Specification For TFT-LCD Module Less Than 3.5":

▼ ~Pt	cincation for if i Ec					(VCI.D01)
NO	Item			Criteri	on	Level
		1. 1The part number is inconsistent with work order of production.				
01	Product condition	1. 2 Mi	ixed prod	luct types.		Major
		1. 3 Ass	sembled	in inverse direction.		Major
02	Quantity	2. 1The	e quantit	y is inconsistent witl	h work order of production	. Major
03	Outline dimension		3. 1 Product dimension and structure must conform to structure diagram.			ure Major
	4 Electrical Testing	4. 1 Mi	issing line	e character and icon		Major
04		4. 2 No	function	or no display.		Major
		4. 3 Display malfunction.				
		4. 4 LCD viewing angle defect.				
		4. 5 Cu	irrent coi	nsumption exceeds p	product specifications.	Major
		1		Item	Acceptance (Q'ty)	
	Dot defect			Bright Dot	≦ 2	
	Dor defect		Dot	Dark Dot	≦ 3	
٥٦	(Bright dot \		Defect	Joint Dot	≦ 2	3.51
05	Dark dot)			Total	≦ 3	Minor
		5. 1 Inspection pattern: full white, full black, Red, Green and				
	On -display			blue screen	ıs.	
				l as dot defect if defe		
		5. 3 Th	e distanc	e between two dot d	lefect ≧5 mm.	



#### ◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item		Criterion						
		6. 1 Round type ( Non-display or display) :							
		Di	Dimension Accep			(Q'ty)			
	DI 1 11	(dia	meter ∶Φ)		A area	B area			
	Black or white dot \ scratch \		$\Phi \le 0.15$		Ignore				
	contamination	0.15	$<\Phi \le 0.20$		2				
	Round type	0.20	$<\Phi \le 0.30$		2	Ignore			
	→ x ← ↓		$\Phi > 0.30$		0				
06	Y		Total		3	-	Minor		
00	$\Phi = (x+y)/2$	6. 2 Line type(	Non-display or	r displa	ny) :		Willion		
	Line type	Dimension		Acceptance (Q'ty)					
	Line type	Length (L)	Length (L) Width (W)		A area	B area			
		W ≤ 0.0		0.03	Ignore				
		→ L I←	→ L I←	L ≦5. 0	0.03 <w td="" ≤<=""><td>0.05</td><td>3</td><td></td><td></td></w>	0.05	3		
				w >	0.05	As round type	I Ignore		
			Total		3				
		D:	ension			(0)			
		1 1	iension ieter∶Φ)		Acceptance ( A area	B area			
	Delester		$\Phi \leq 0.20$		gnore				
07	Polarizer Bubble	0.20 <	$\Phi \leq 0.50$		3	Ignore	Minor		
			$\Phi > 0.50$		0	Ignore			
		Т	otal		3				



## lacktriangle Specification For TFT-LCD Module Less Than 3.5":

NO	Item		Criterion		Level
	Item  The crack of glass	Symbols:  X: The let Z: The thit: The thit  8. 1 Genera  8. 1. 1 Chit	egth of crack ickness of crack ckness of glass  1 glass chip: p on panel surface and crack Y [OK]  Seal width	Z X SP [NG]	Level
		X	Y	Z	
		≦ a	Crack can't enter viewing area	≦1/2 t	
		≦ a	Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	



## ◆Specification For TFT-LCD Module Less Than 3, 5":

NO	Item		Criterio	n	Level
		Z: The thi t: The thi 8. 1. 2 Corn	ngth of crack ickness of crack ckness of glass ner crack :	Y: The width of crack. W: terminal length a: LCD side length	
		X	Y Crack can't enter	Z	
		≦1/5 a	viewing area	Z ≤ 1/2 t	
		≦1/5 a	Crack can't exceed th half of SP width.	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	
08	The crack of glass	0.0.0			Minor
			sion over terminal: p on electrode pad:		
		W Y	Z X	X Y Y Y Y Y Y Y Y Y Y Y Y Y Y Y Y Y Y Y	Z
			X	Y Z	]
		Front		$\begin{array}{c cc} 1/2 & \leq t \\ \leq W & \leq 1/2 t \end{array}$	_
		Back	≦ a ≦	≥ vv   ≥ 1/2 t	



# ◆Specification For TFT-LCD Module Less Than 3.5″:

NO	Item	Criterion	Level
		X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 2. 2 Non-conductive portion:	
08	The crack of glass	<ul> <li>X</li> <li>Y</li> <li>Z</li> <li>≤ 1/3 a</li> <li>≤ W</li> <li>≤ t</li> <li>O If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> </ul>	Minor
		8. 2. 3 Glass remain : $\begin{array}{c cccc} X & Y & Z \\ & \leq a & \leq 1/3 \ W & \leq t \end{array}$	



# lacktriangle Specification For TFT-LCD Module Less Than 3. 5":

NO	Item	Criterion	Level
		9, 1 Backlight can't work normally.	Major
09	Backlight elements	9, 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
10	diagram.  10. 2 No short circuits in components on PCB or FP  10. 3 Parts on PCB or FPC must be the same as on characteristic chart . There should be no missing parts or excess parts.  General appearance  10. 4 Product packaging must the same as specified specification sheet.  10. 5 The folding and peeled off in polarizer are not	10. 1 Pin type \quantity \dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is ≤1.5 mm.	Minor



## RELIABILITY TEST

(Ver.B01)

NO.   TEST ITEM   TEST CONDITION	<u> </u>				
Storage Test  Low Temperature Storage Test  High Temperature / High Humidity Storage Test  Temperature Cycling Storage Test  Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance: 15°C ~35°C 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge (time between successive discharges at least form of the output voltage indication: ±5%)  Vibration Test (Packaged)  Vibration Test (Packaged)  Vibration Test (Packaged)  Reep in 30 ±15°C 240 hrs  Keep in -30 ±5°C 240 hrs  Single Discharge:  (30mins) (5mins) (30mins) (5mins)  20 Cycle  Contact Discharge: Apply 250 V with 5 times discharge: Apply 250 V with 5 times discharge for each polarity +/-  1. Temperature ambiance: 15°C ~35°C 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge Resistance(Rd): 330 Ω±10% 5. Discharge, mode of operation: Single Discharge (time between successive discharges at least form of the output voltage indication: ±5%)  1. Sine wave 10~55 Hz frequency (1 min/sweep) 2. The amplitude of vibration: 1.5 mm 3. Each direction (X · Y · Z) duration for 2 Hrs					
Storage Test  High Temperature / High Humidity Storage Test  Temperature Cycling Storage Test  Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance: 15℃ ~35℃ 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge, mode of operation: Single Discharge (time between successive discharges at least (Tolerance if the output voltage indication: ±5%)  Vibration Test (Packaged)  Feed in 60 ℃ / 90% R.H duration for 240 hrs  (Excluding the polarizer)  Contact Discharge: Apply 250 V with 5 times discharge for each polarity +/- 1. Temperature ambiance: 15℃ ~35℃ 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge Resistance(Rd): 330Ω±10% 5. Discharge (time between successive discharges at least (Tolerance if the output voltage indication: ±5%)  1. Sine wave 10~55 Hz frequency (1 min/sweep) 2. The amplitude of vibration: 1.5 mm 3. Each direction (X · Y · Z) duration for 2 Hrs					
High Humidity Storage Test  Temperature Cycling Storage Test  Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance: 15°C ~35°C 2. Humidity relative: 30% ~60% 3. Energy Storage Capacitance(Cs+Cd): 150pF±10% 4. Discharge, mode of operation: Single Discharge (time between successive discharges at least (Tolerance if the output voltage indication: ±5%)  Vibration Test (Packaged)  Vibration Test (Packaged)  Keep in 60° C 790% K.H duration for 240 ins (Excluding the polarizer)  -30°C → +25°C → 80°C → +25°C (30mins) (5mins) (30mins) (5mins)  (30mins) (5mins)  (30mins) (5mins) (30mins) (5mins) (30mins) (5mins)  (30mins) (5mins)  (30mins) (5mins)  (30mins) (5mins) (30mins) (5mins)  (30mins) (5mins) (30mins) (					
Temperature Cycling Storage Test    (30mins) (5mins) (30mins) (5mins)   20 Cycle					
Storage Test    Storage Test   Storage Test   Storage Test   20 Cycle					
Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/-  1. Temperature ambiance : 15°C ~35°C 2. Humidity relative : 30% ~60% 3. Energy Storage Capacitance(Cs+Cd) : 150pF±10% 4. Discharge Resistance(Rd) : 330Ω±10% 5. Discharge, mode of operation : Single Discharge (time between successive discharges at least (Tolerance if the output voltage indication : ±5%)  1. Sine wave 10~55 Hz frequency (1 min/sweep) 2. The amplitude of vibration :1.5 mm 3. Each direction (X · Y · Z) duration for 2 Hrs  Packing Weight (Kg) Drop Height (cm)					
Apply 2 KV with 5 times  Discharge for each polarity +/-  1. Temperature ambiance : 15°C ~35°C  2. Humidity relative : 30% ~60%  3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%  4. Discharge Resistance(Rd) : 330 Ω±10%  5. Discharge, mode of operation :  Single Discharge (time between successive discharges at least (Tolerance if the output voltage indication : ±5%)  1. Sine wave 10~55 Hz frequency (1 min/sweep)  2. The amplitude of vibration :1.5 mm  3. Each direction (X · Y · Z) duration for 2 Hrs  Packing Weight (Kg) Drop Height (cm)					
Discharge for each polarity +/-   discharge for each polarity +/-     1. Temperature ambiance : 15°C ~35°C     2. Humidity relative : 30% ~60%     3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%     4. Discharge Resistance(Rd) : 330Ω±10%     5. Discharge, mode of operation :     Single Discharge (time between successive discharges at least (Tolerance if the output voltage indication : ±5%)     1. Sine wave 10~55 Hz frequency (1 min/sweep)     2. The amplitude of vibration :1.5 mm     3. Each direction (X · Y · Z) duration for 2 Hrs     Packing Weight (Kg)   Drop Height (cm)					
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Vibration Test (Packaged)  2. The amplitude of vibration :1.5 mm 3. Each direction (X \ Y \ Z) duration for 2 Hrs  Packing Weight (Kg) Drop Height (cm)					
(Packaged)  2. The amplitude of vibration :1.5 mm  3. Each direction (X \ Y \ Z) duration for 2 Hrs  Packing Weight (Kg) Drop Height (cm)					
3. Each direction (X · Y · Z) duration for 2 Hrs  Packing Weight (Kg) Drop Height (cm)					
0 ~ 45. 4 122					
7 Drop Test 45. 4 ~ 90. 8 76					
7 (Packaged) 90.8 ~ 454 61					
Over 454 46					
Drop Direction: **1 corner / 3 edges / 6 sides each 1time					

#### OResult Evaluation Criteria:

Under the display quality test conditions with normal operations with normal operation state. Do not change these conditions as such changes may affect practical display function. (Normal operation state)

Temperature: +20~30℃ **Humidity** : 50~70%

Atmospheric pressure: 86~106Kpa



#### 5. PRECAUTION RELATING PRODUCT HANDLING

#### 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### **5.2 HANDLING**

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

#### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}$ C  $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

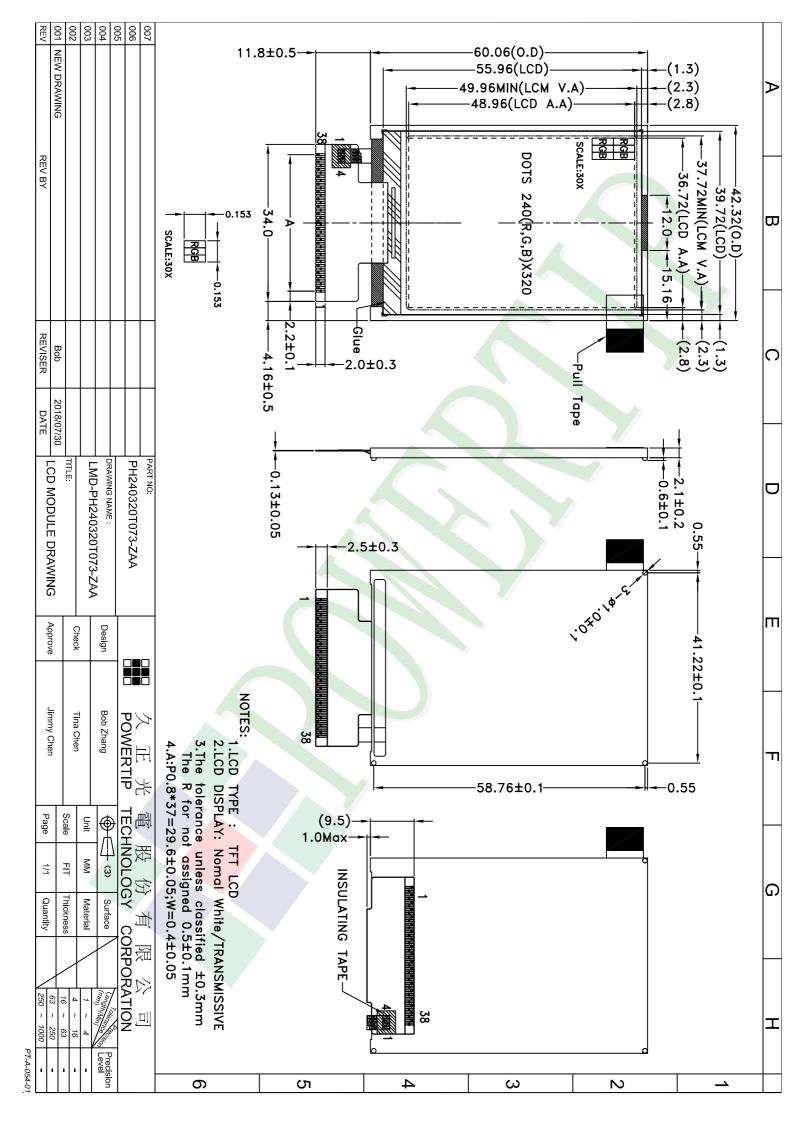
#### **5.4 TERMS OF WARRANTY**

5.4.1 Applicable warrant period

The period is within Twenty-four months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Approve Contact Check Ver.001 LCM包裝規格書 Tina Chen Jimmy Chen Jimmy Chen Documents NO. PKG-PH240320T073-ZAA LCM Packaging Specifications 1.包裝材料規格表 (Packaging Material): (per carton) No. Total Weight Item Model Dimensions (mm) 1Pcs Weight Quantity 1 成品 (LCM) PH240320T073-ZAA 42.32 X 60.06 0.0075 468 3.51 2 靜電袋(1)Antistatic Bag 100 X 100 0.0011 0.5148 BAG100100ARABA 468 3 氣泡袋(2)Bubble Bag 100 X 65 0.3744 BAG100065BRABA 0.0008 468 4 A1-1隔板(3)A1-1 Partition 295 X 47 X 3 0.0078 1.3104 BX29500047BZBA 168 5 B1-1隔板(4)B1-1 Partition BX24500047BZBA 245 X 47 X 3 0.0065 48 0.312 6 280 X 240 24 氣泡紙(5)Bubble Sheet BAG280240BWABA 0.006 0.144 7 C1内盒(6)Product Box BX31025555AABA 310 X 255 X 55 0.13 12 1.56 8 外紙箱(7)Carton BX52732536CCBA 527 X 325 X 360 0.83 1 0.83 9 2.一 整箱總重量 (Total LCD Weight in carton): Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity): (1)Quantity Of Spacer: A1-1隔板 X 14, B1-1隔板 X (2) Total LCM quantity in carton: quantity per box x no of boxes 12 468 (5) 氣泡紙 **Bubble Sheet** (1)靜電袋+(2)氣泡袋+LCM Antistatic Bag+Bubble Bag+LCM (3)(4)隔板 Partition ₩ (註 Remark 1) (5) 氣泡紙 **Bubble Sheet** ĺŀ (7)外紙箱 Carton (6) C1內盒 Product Box 特 記 事 項 (REMARK) 4. LCM排放示意圖(前後間隔不放置): 4. LCM placed as figure showing: (First and last slot should be empty)

Ø 模組(LCM) X 1pcs.